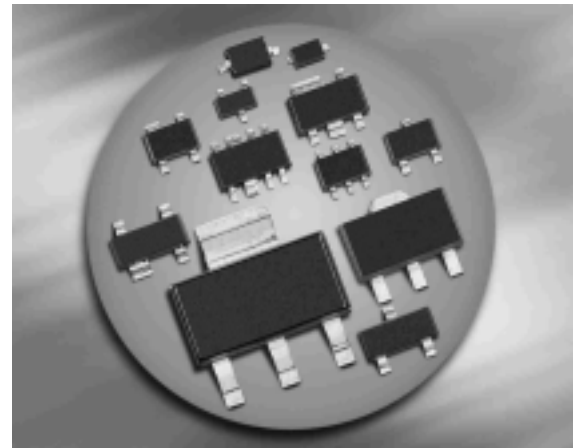
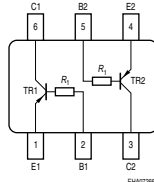
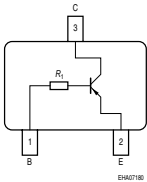


**PNP Silicon Digital Transistor**

- Switching circuit, inverter, interface circuit, driver circuit
- Built in bias resistor ( $R_1 = 4.7 \text{ k}\Omega$ )
- BCR169S / U: Two internally isolated transistors with good matching in one multichip package
- BCR169S / U: For orientation in reel see package information below


**BCR169/F/L3  
BCR169T/W**
**BCR169S/U**


Type	Marking	Pin Configuration						Package
BCR169	WSs	1=B	2=E	3=C	-	-	-	SOT23
BCR169F	WSs	1=B	2=E	3=C	-	-	-	TSFP-3
BCR169L3	WS	1=B	2=E	3=C	-	-	-	TSLP-3-4
BCR169S	WSs	1=E1	2=B1	3=C2	4=E2	5=B2	6=C1	SOT363
BCR169T	WS	1=B	2=E	3=C	-	-	-	SC75
BCR169U	WSs	1=E1	2=B1	3=C2	4=E2	5=B2	6=C1	SC74
BCR169W	WSs	1=B	2=E	3=C	-	-	-	SOT323

**Maximum Ratings**

Parameter	Symbol	Value	Unit	
Collector-emitter voltage	$V_{CEO}$	50	V	
Collector-base voltage	$V_{CBO}$	50		
Input forward voltage	$V_{i(fwd)}$	30		
Input reverse voltage	$V_{i(rev)}$	5		
Collector current	$I_C$	100	mA	
Total power dissipation	$P_{tot}$		mW	
BCR169, $T_S \leq 102^\circ\text{C}$				200
BCR169F, $T_S \leq 128^\circ\text{C}$				250
BCR169L3, $T_S \leq 135^\circ\text{C}$				250
BCR169S, $T_S \leq 115^\circ\text{C}$				250
BCR169T, $T_S \leq 109^\circ\text{C}$				250
BCR169U, $T_S \leq 118^\circ\text{C}$				250
BCR169W, $T_S \leq 124^\circ\text{C}$				250
Junction temperature	$T_j$	150	°C	
Storage temperature	$T_{stg}$	-65 ... 150		

**Thermal Resistance**

Parameter	Symbol	Value	Unit	
Junction - soldering point <sup>1)</sup>	$R_{thJS}$		K/W	
BCR169				$\leq 240$
BCR169F				$\leq 90$
BCR169L3				$\leq 60$
BCR169S				$\leq 140$
BCR169T				$\leq 165$
BCR169U				$\leq 133$
BCR169W				$\leq 105$

<sup>1)</sup>For calculation of  $R_{thJA}$  please refer to Application Note Thermal Resistance

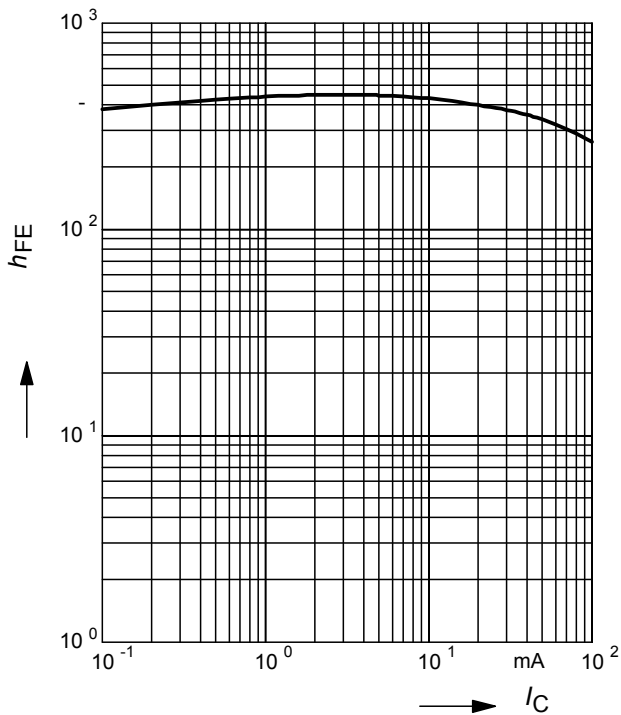
**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>DC Characteristics</b>					
Collector-emitter breakdown voltage $I_C = 100 \mu\text{A}, I_B = 0$	$V_{(BR)CEO}$	50	-	-	V
Collector-base breakdown voltage $I_C = 10 \mu\text{A}, I_E = 0$	$V_{(BR)CBO}$	50	-	-	
Collector-base cutoff current $V_{CB} = 40 \text{ V}, I_E = 0$	$I_{CBO}$	-	-	100	nA
Emitter-base cutoff current $V_{EB} = 5 \text{ V}, I_C = 0$	$I_{EBO}$	-	-	100	nA
DC current gain <sup>1)</sup> $I_C = 5 \text{ mA}, V_{CE} = 5 \text{ V}$	$h_{FE}$	120	-	630	-
Collector-emitter saturation voltage <sup>1)</sup> $I_C = 10 \text{ mA}, I_B = 0.5 \text{ mA}$	$V_{CEsat}$	-	-	0.3	V
Input off voltage $I_C = 100 \mu\text{A}, V_{CE} = 5 \text{ V}$	$V_{i(off)}$	0.4	-	0.8	
Input on voltage $I_C = 2 \text{ mA}, V_{CE} = 0.3 \text{ V}$	$V_{i(on)}$	0.5	-	1.1	
Input resistor	$R_1$	3.2	4.7	6.2	k $\Omega$
<b>AC Characteristics</b>					
Transition frequency $I_C = 10 \text{ mA}, V_{CE} = 5 \text{ V}, f = 100 \text{ MHz}$	$f_T$	-	200	-	MHz
Collector-base capacitance $V_{CB} = 10 \text{ V}, f = 1 \text{ MHz}$	$C_{cb}$	-	3	-	pF

<sup>1)</sup>Pulse test:  $t < 300 \mu\text{s}$ ;  $D < 2\%$

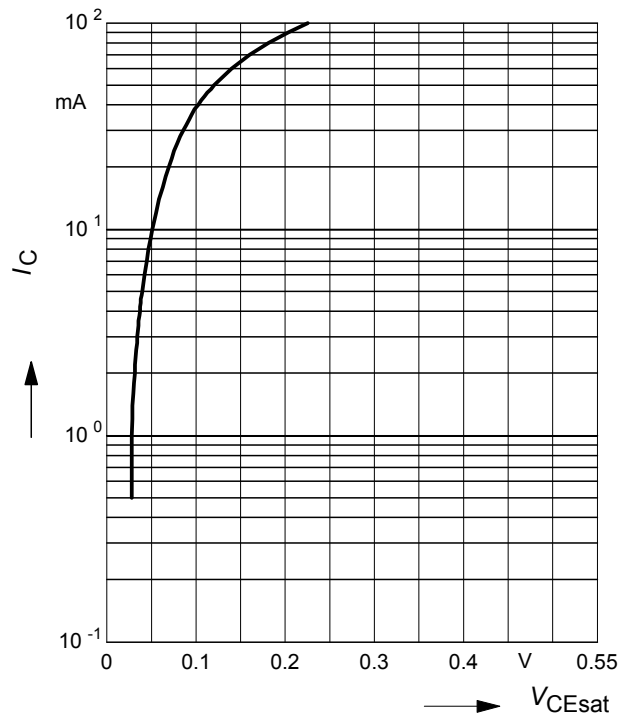
**DC current gain  $h_{FE} = f(I_C)$**

$V_{CE} = 5\text{ V}$  (common emitter configuration)



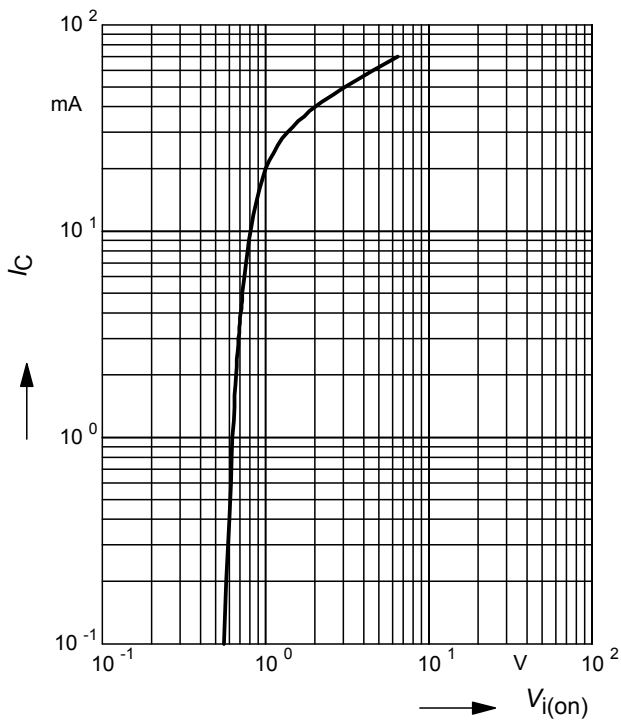
**Collector-emitter saturation voltage**

$V_{CEsat} = f(I_C), h_{FE} = 20$



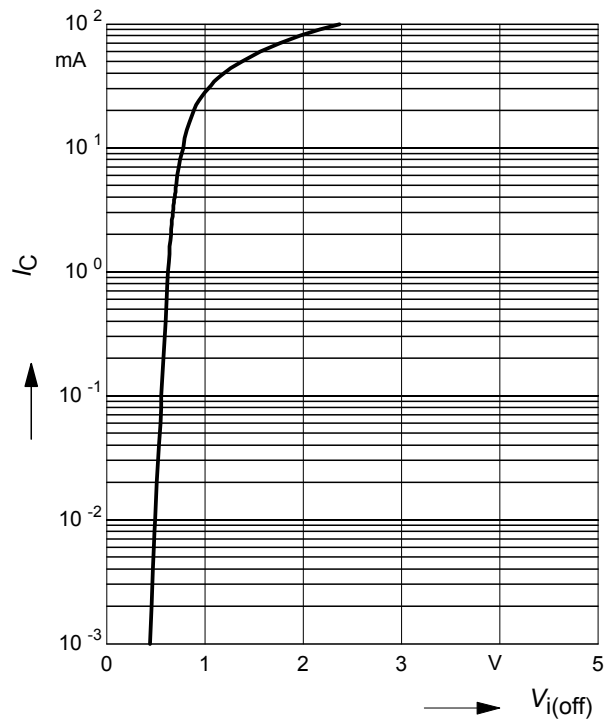
**Input on Voltage  $V_{i(on)} = f(I_C)$**

$V_{CE} = 0.3\text{ V}$  (common emitter configuration)



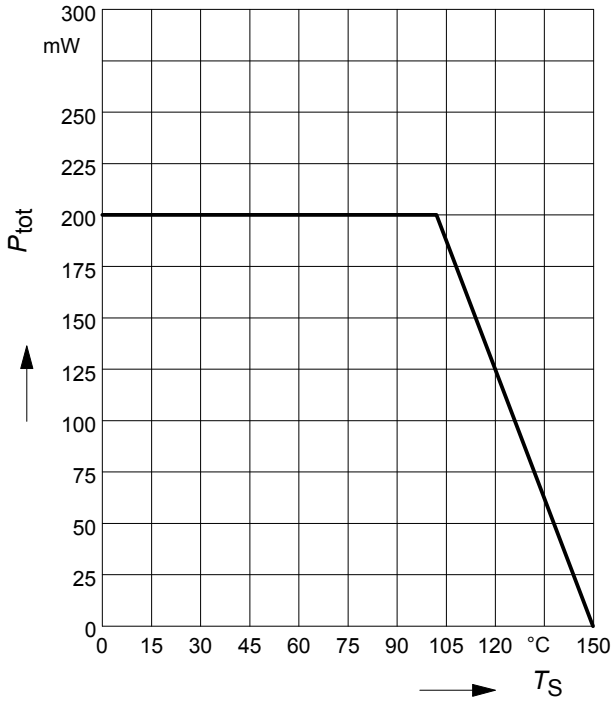
**Input off voltage  $V_{i(off)} = f(I_C)$**

$V_{CE} = 5\text{ V}$  (common emitter configuration)



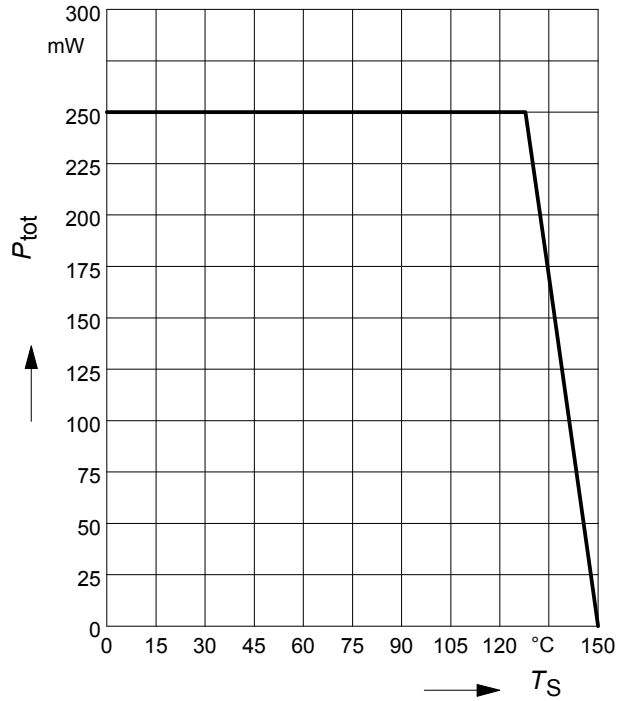
Total power dissipation  $P_{tot} = f(T_S)$

BCR169



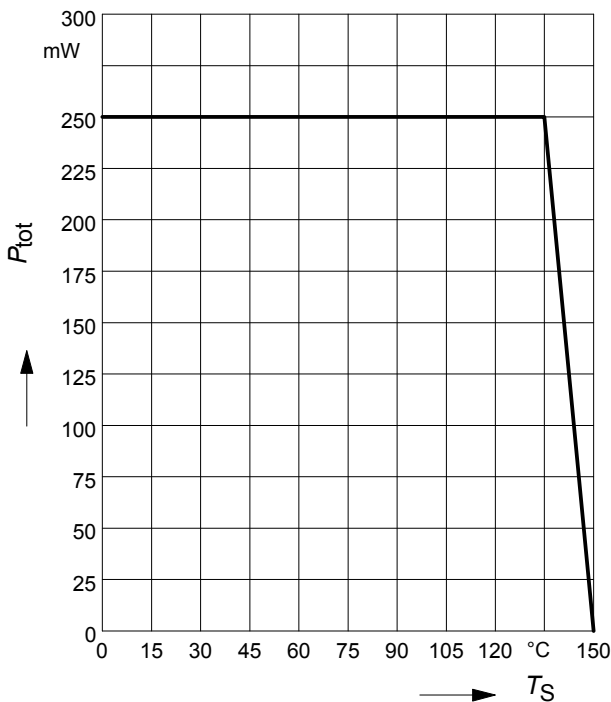
Total power dissipation  $P_{tot} = f(T_S)$

BCR169F



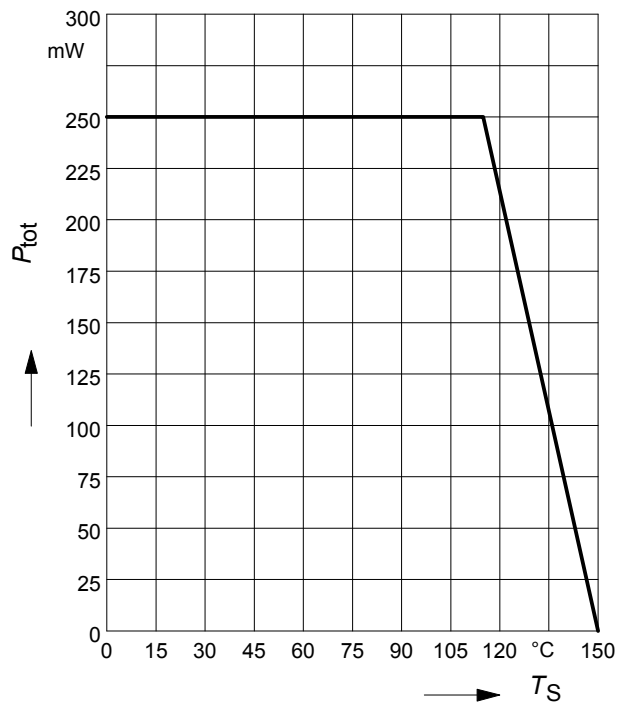
Total power dissipation  $P_{tot} = f(T_S)$

BCR169L3



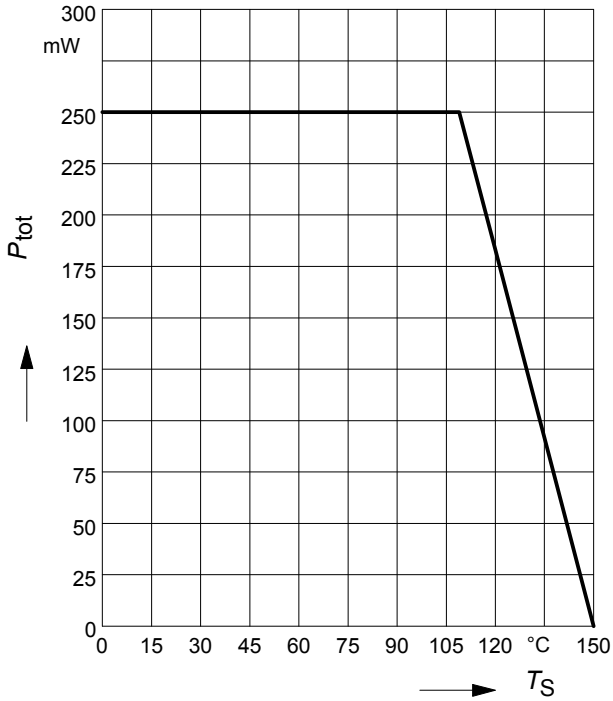
Total power dissipation  $P_{tot} = f(T_S)$

BCR169S



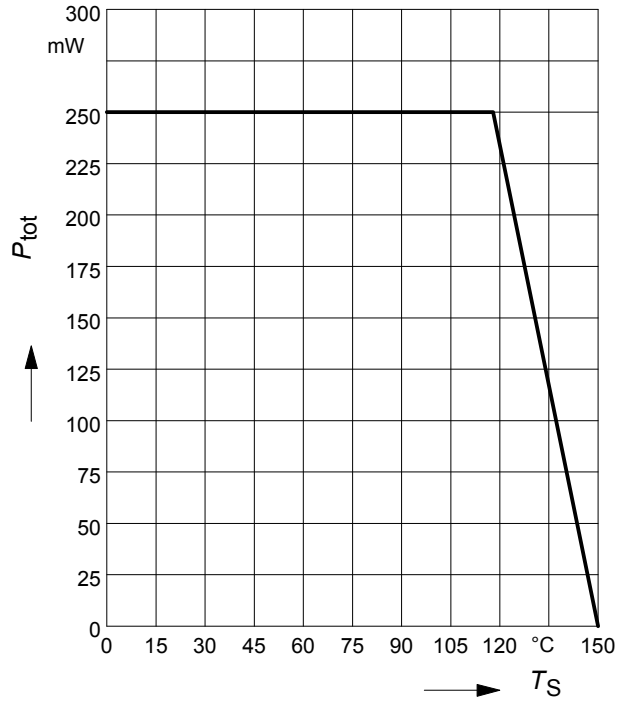
Total power dissipation  $P_{tot} = f(T_S)$

BCR169T



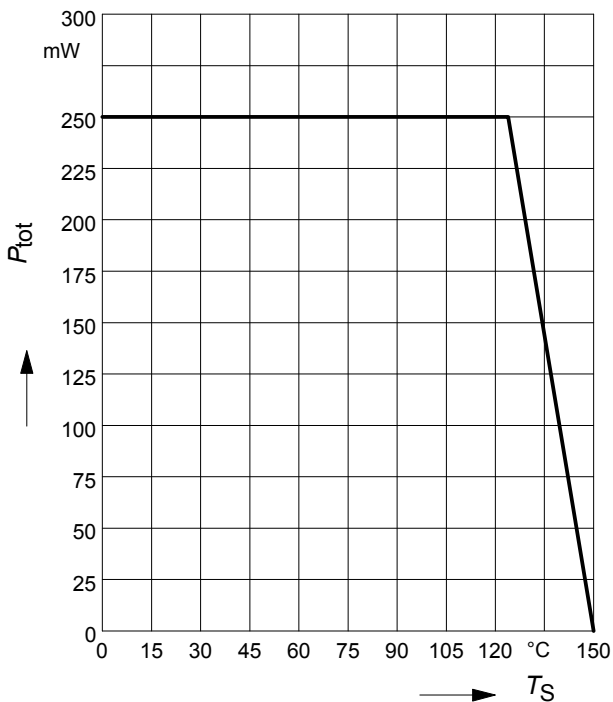
Total power dissipation  $P_{tot} = f(T_S)$

BCR169U



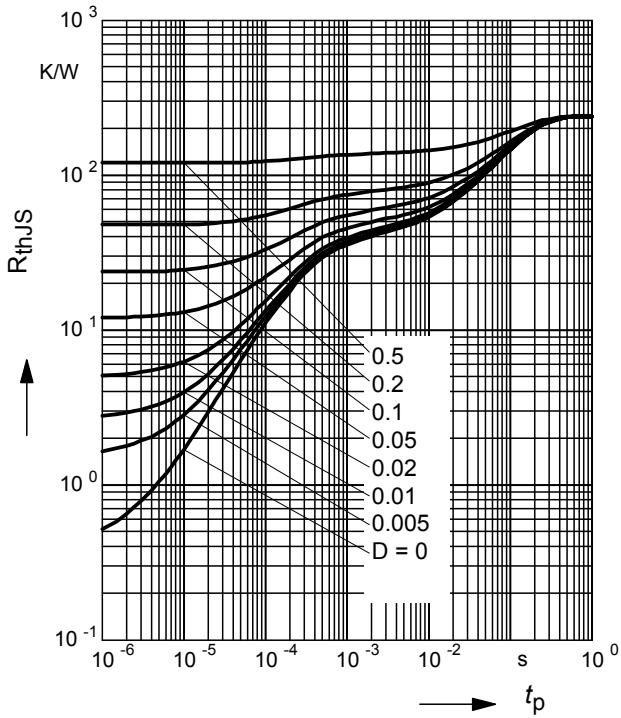
Total power dissipation  $P_{tot} = f(T_S)$

BCR169W



**Permissible Pulse Load  $R_{thJS} = f(t_p)$**

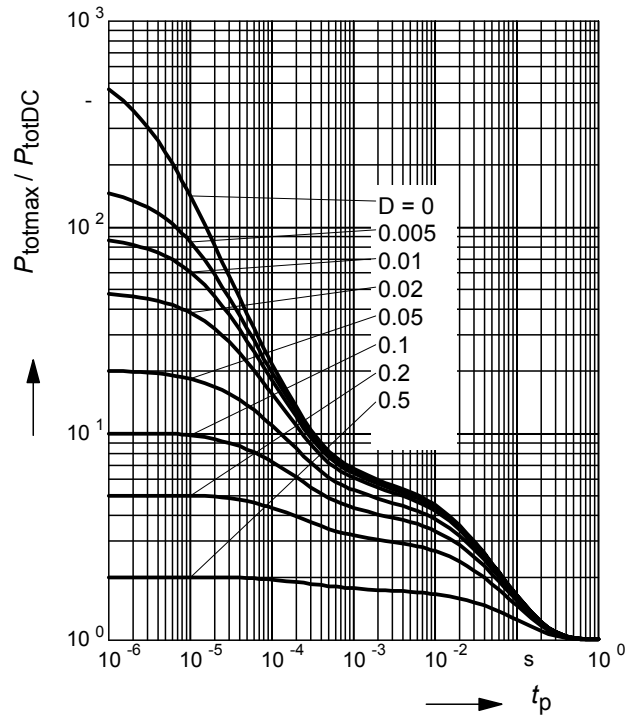
BCR169



**Permissible Pulse Load**

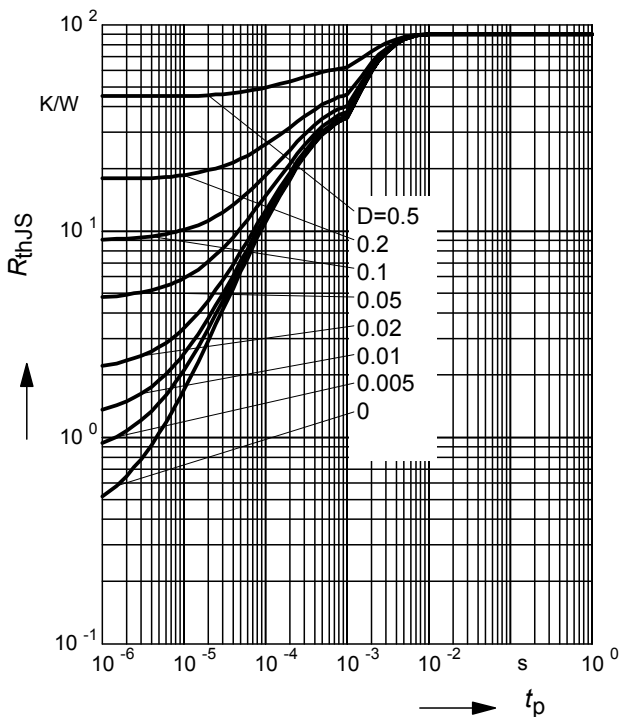
$P_{totmax}/P_{totDC} = f(t_p)$

BCR169



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

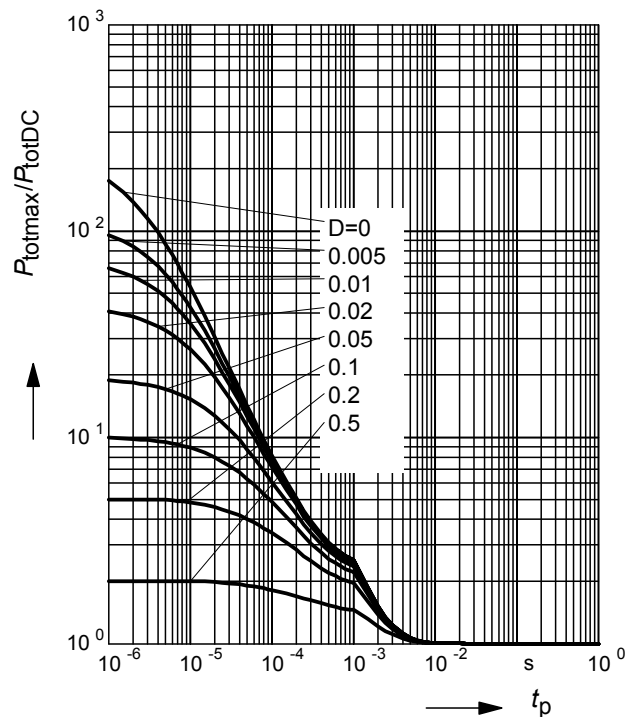
BCR169F



**Permissible Pulse Load**

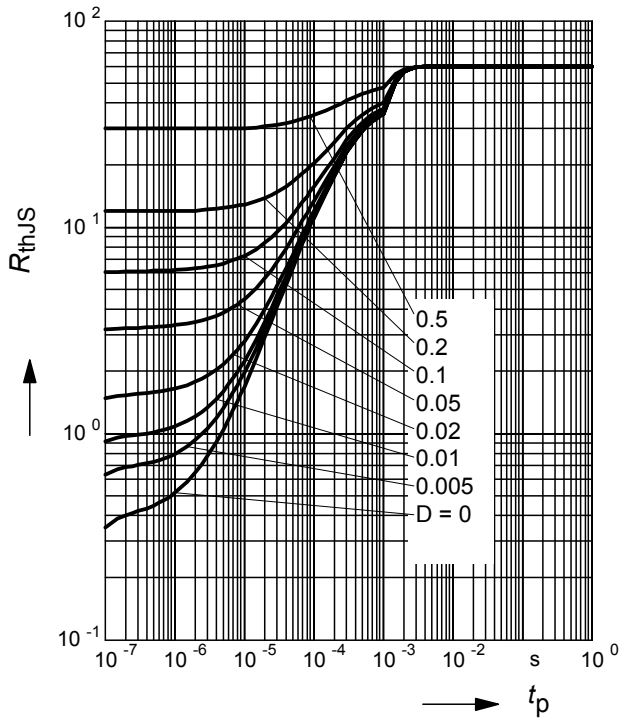
$P_{totmax}/P_{totDC} = f(t_p)$

BCR169F



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

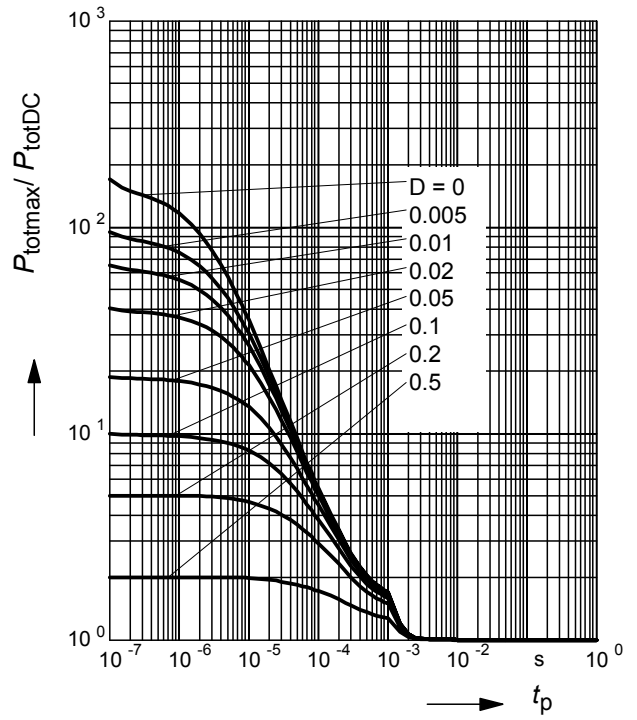
BCR169L3



**Permissible Pulse Load**

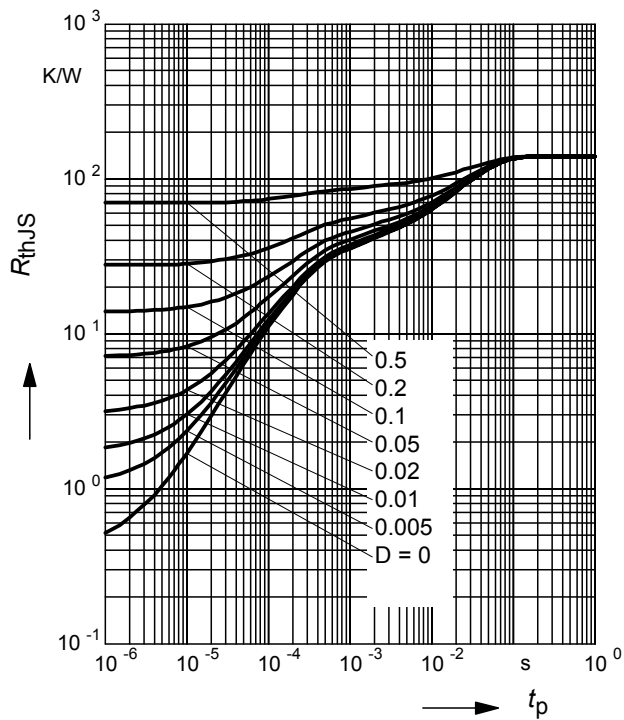
$P_{totmax}/P_{totDC} = f(t_p)$

BCR169L3



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

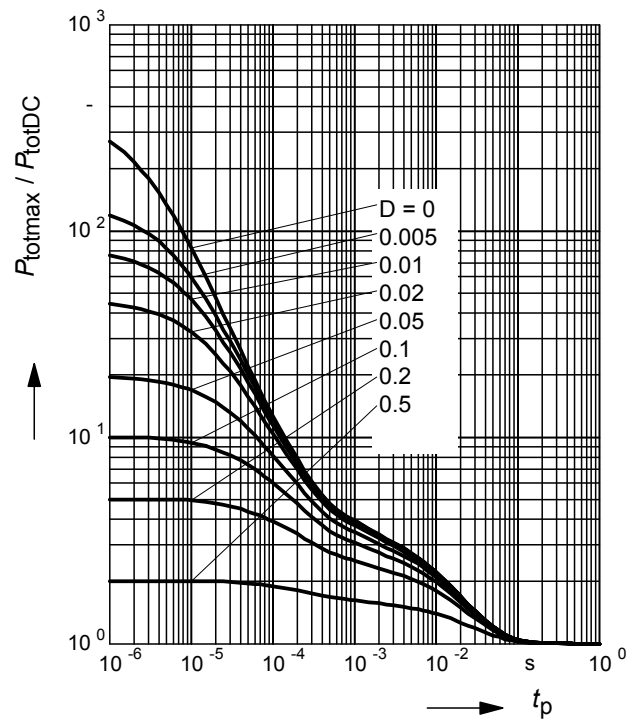
BCR169S



**Permissible Pulse Load**

$P_{totmax}/P_{totDC} = f(t_p)$

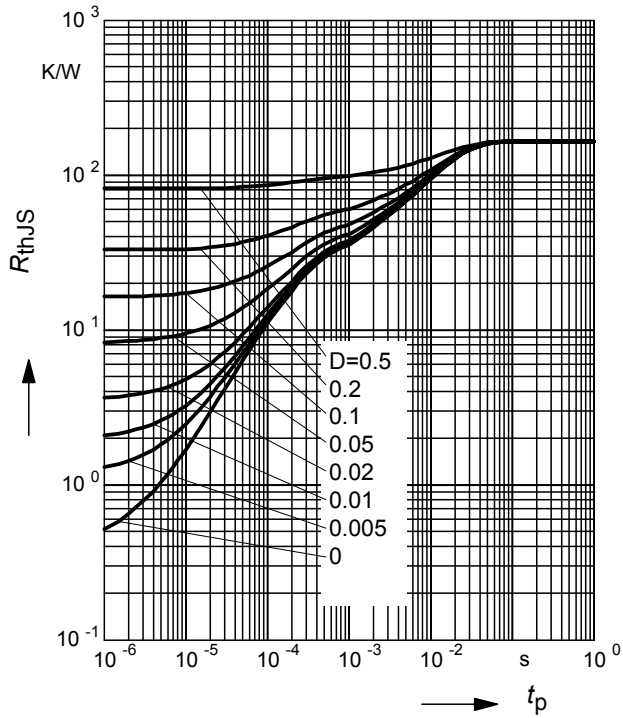
BCR169S





**Permissible Puls Load  $R_{thJS} = f(t_p)$**

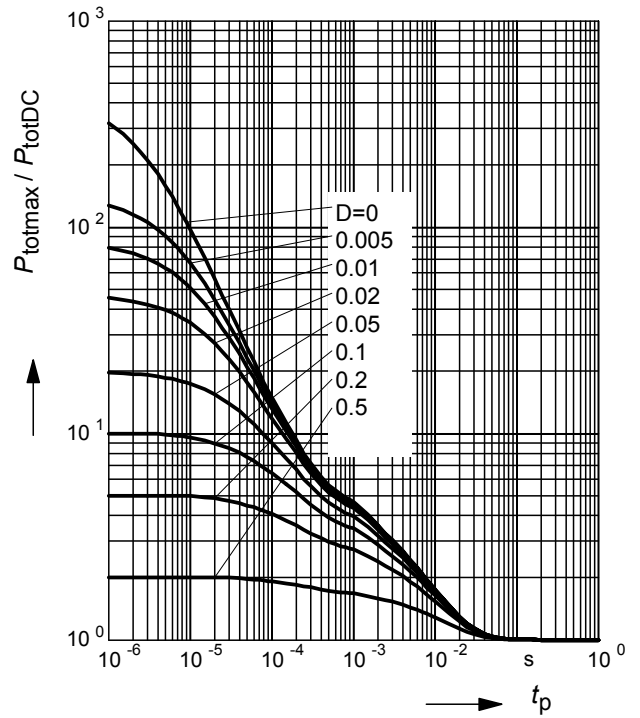
BCR169T



**Permissible Pulse Load**

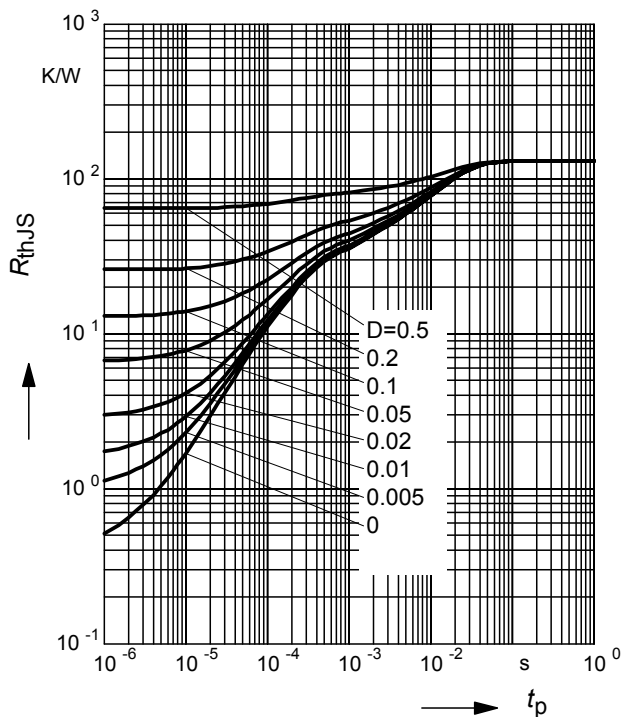
$P_{totmax}/P_{totDC} = f(t_p)$

BCR169T



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

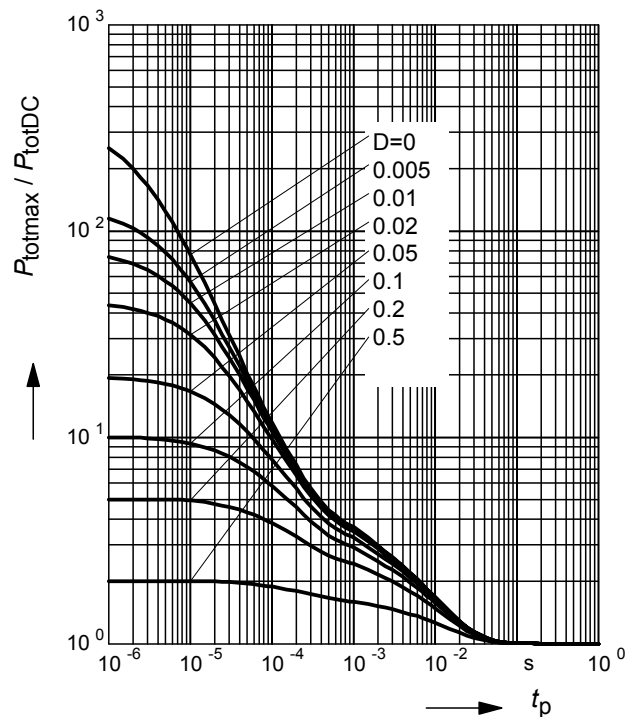
BCR169U



**Permissible Pulse Load**

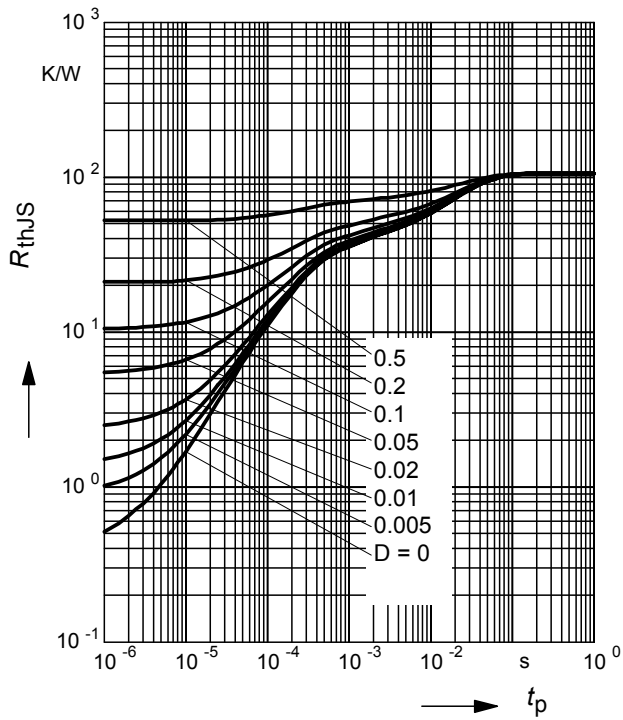
$P_{totmax}/P_{totDC} = f(t_p)$

BCR169U



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

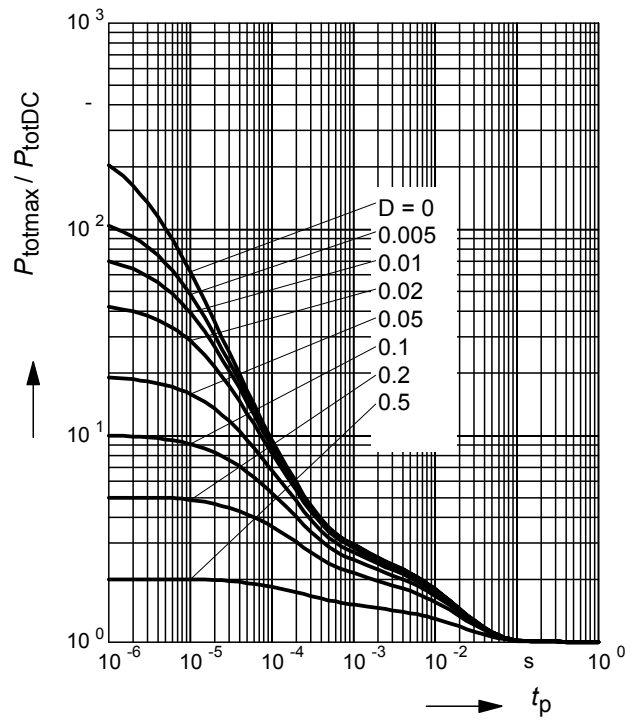
BCR169W



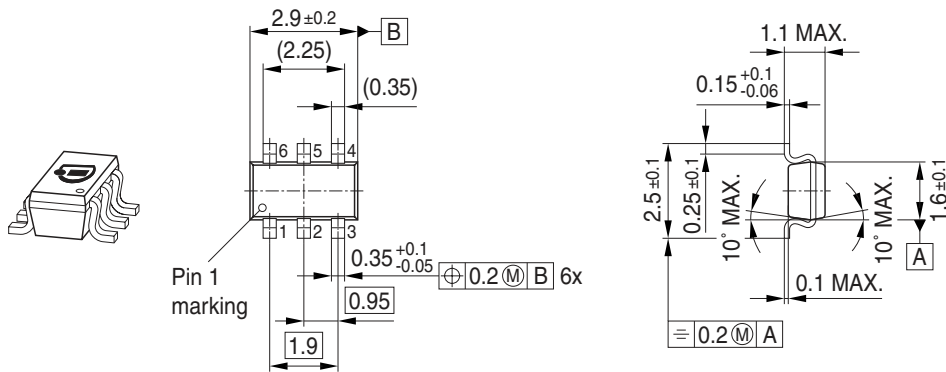
**Permissible Pulse Load**

$P_{totmax}/P_{totDC} = f(t_p)$

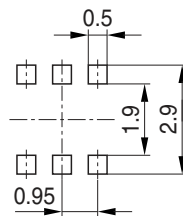
BCR169W



Package Outline

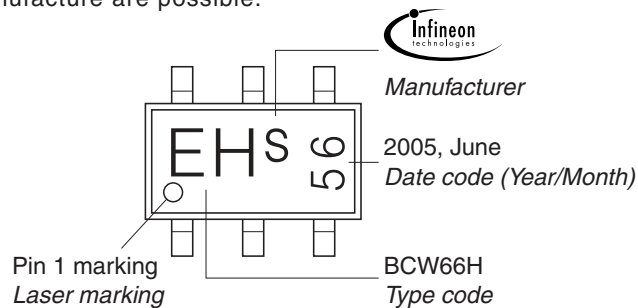


Foot Print



Marking Layout (Example)

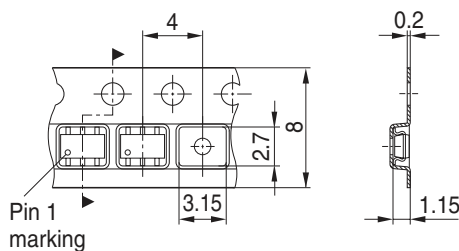
Small variations in positioning of Date code, Type code and Manufacture are possible.



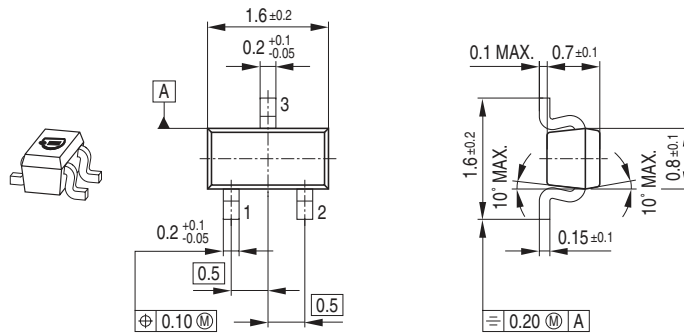
Standard Packing

Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel

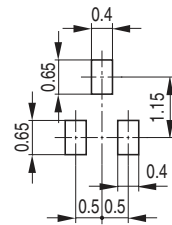
For symmetric types no defined Pin 1 orientation in reel.



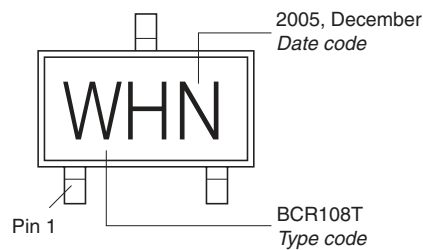
Package Outline



Foot Print

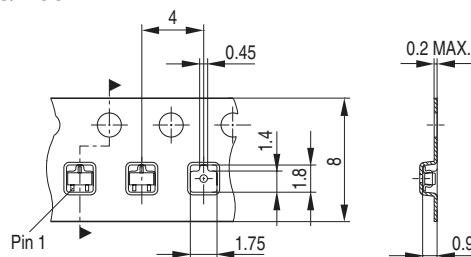


Marking Layout (Example)



Standard Packing

Reel  $\phi$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\phi$ 330 mm = 10.000 Pieces/Reel

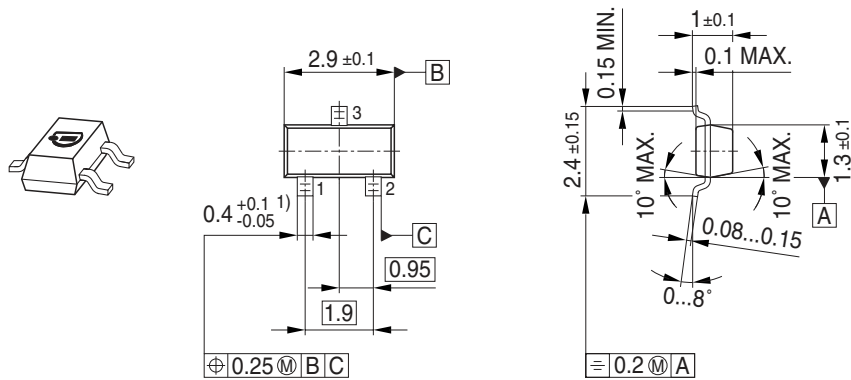


Date Code marking for discrete packages with one digit (SCD80, SC79, SC75<sup>1)</sup>) CES-Code

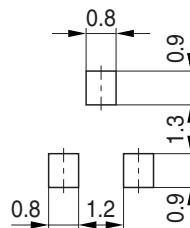
Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	a	p	A	P	a	p	A	P	a	p	A	P
02	b	q	B	Q	b	q	B	Q	b	q	B	Q
03	c	r	C	R	c	r	C	R	c	r	C	R
04	d	s	D	S	d	s	D	S	d	s	D	S
05	e	t	E	T	e	t	E	T	e	t	E	T
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	v	G	V	g	v	G	V	g	v	G	V
08	h	x	H	X	h	x	H	X	h	x	H	X
09	j	y	J	Y	j	y	J	Y	j	y	J	Y
10	k	z	K	Z	k	z	K	Z	k	z	K	Z
11	l	2	L	4	l	2	L	4	l	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

1) New Marking Layout for SC75, implemented at October 2005.

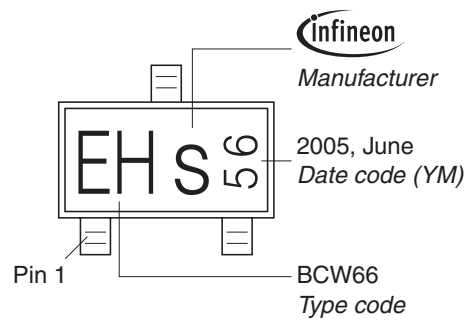
Package Outline



Foot Print

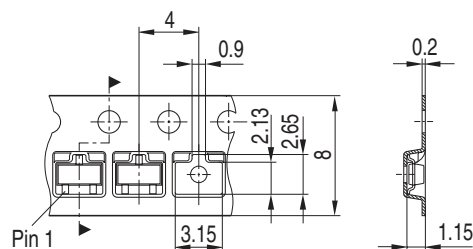


Marking Layout (Example)

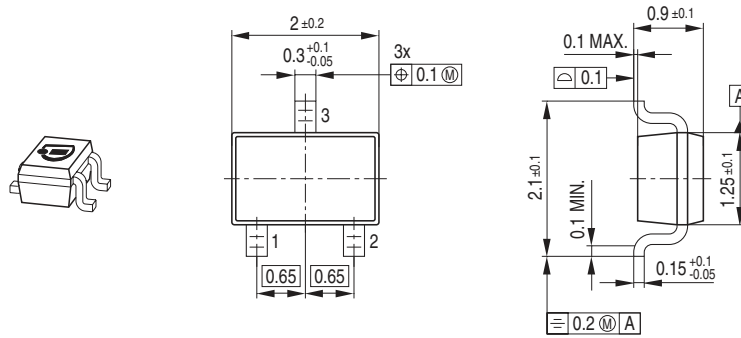


Standard Packing

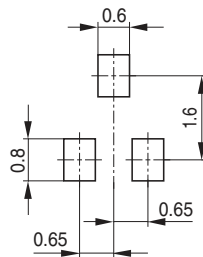
Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel



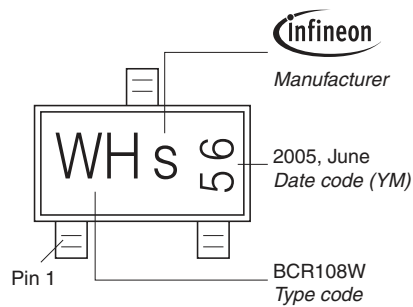
Package Outline



Foot Print

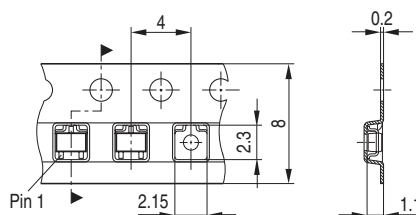


Marking Layout (Example)

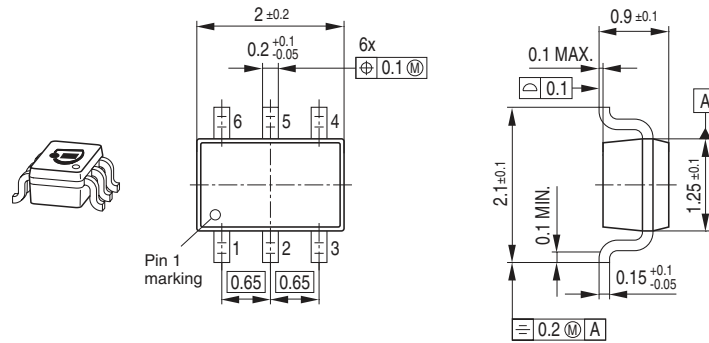


Standard Packing

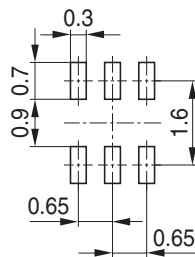
Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel



### Package Outline

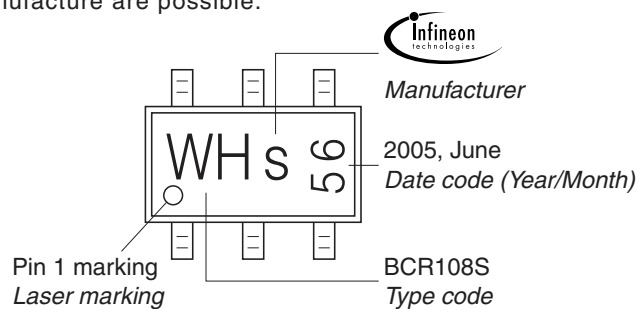


### Foot Print



### Marking Layout (Example)

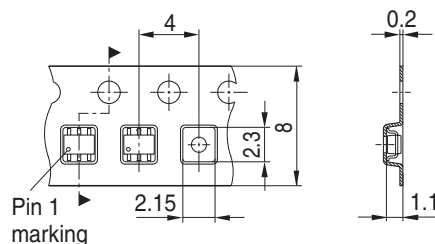
Small variations in positioning of Date code, Type code and Manufacture are possible.



### Standard Packing

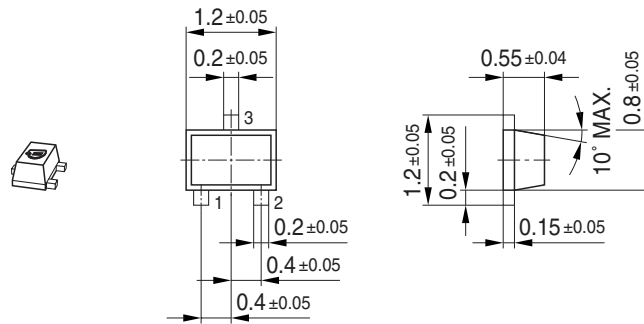
Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.

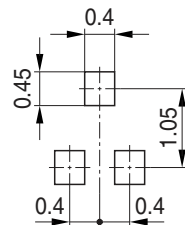




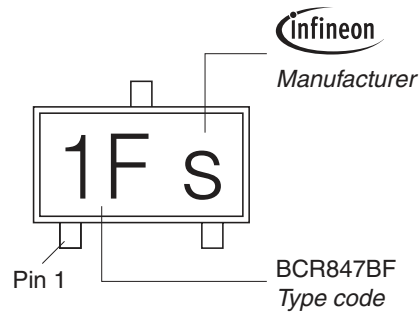
Package Outline



Foot Print

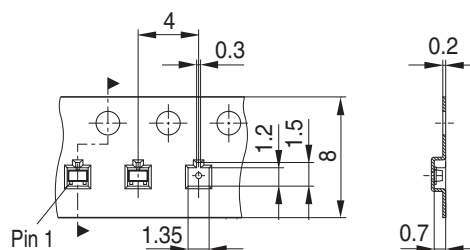


Marking Layout (Example)

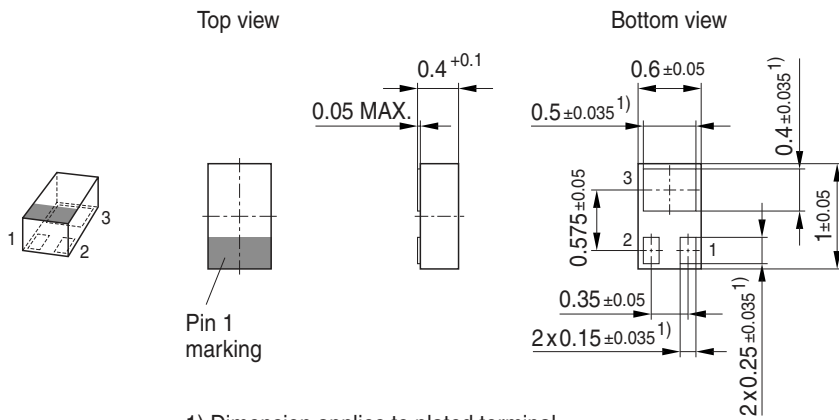


Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel  
 Reel ø330 mm = 10.000 Pieces/Reel



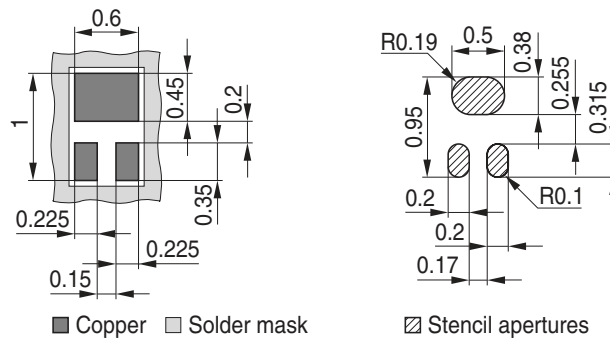
### Package Outline



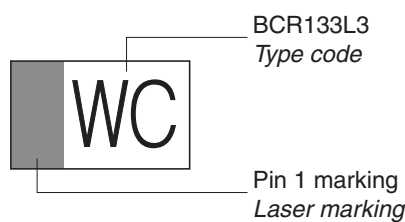
1) Dimension applies to plated terminal

### Foot Print

For board assembly information please refer to Infineon website "Packages"

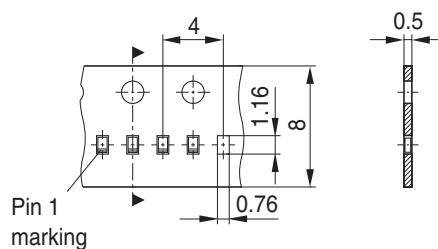


### Marking Layout



### Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



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